

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.29854	100.0	6.3
			Subtotal	0.29854	100	6.3
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.13541	100.0	2.85748
	Pure metal	Aluminium (Al)	7429-90-5	0.00628	100.0	0.13254
			Subtotal	0.14169	200	2.99002
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.09478	10.0	2
	Silver alloy	Silver (Ag)	7440-22-4	0.01896	2.0	0.4
	Lead alloy	Lead (Pb)	7439-92-1	0.83403	88.0	17.6
			Subtotal	0.94777	100	20
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00696	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00464	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00696	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.02553	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	23.16598	99.81	488.8594
			Subtotal	23.21007	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.24485	100.0	5.167
			Subtotal	0.24485	100	5.167
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	2.25471	3.0	47.58
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.50942	6.0	95.16
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	7.51571	10.0	158.6
	Carbon Black	Carbon black	1333-86-4	0.37579	0.5	7.93
	Filler	Misc. Silica compounds (generic)	14808-60-7	58.62252	78.0	1237.08
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	1.87893	2.5	39.65
			Subtotal	75.15708	100	1586
			Total	100	100	2110.24703

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.